Product Summary

V _{(BR)DSS}	R _{DS(on)TYP}	l _D
100V	1.8mΩ@10V	260A



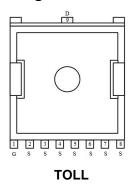
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

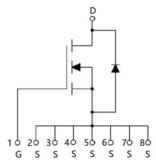
Applications

- PWM Application
- Hard switched and high frequency circuits
- Power Management

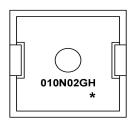
Package



Circuit diagram



Marking



010N02GH : Product code * : Month code

Order Information

Device	Package	Unit/Tape
SP010N02BGHTO	TOLL	2000

100V N-Channel Power MOSFET

Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage		±20	V
Continuous Drain Current1 (Tc=25°C)	I _D	260	Α
Continuous Drain Current1 (Tc=100°C)	I _D	175	Α
Pulsed Drain Current	I _{DM}	1040	Α
Single Pulse Avalanche Energy ¹	Eas	1560	mJ
Power Dissipation (Tc=25°C)	P _D	280	W
Thermal Resistance Junction-to-Case R _{0JC} 0.45		0.45	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	$^{\circ}$
Operating Junction Temperature Range	TJ	-55 to 150	$^{\circ}$ C

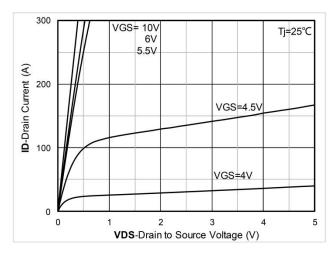
Electrical characteristics (Ta=25°C, unless otherwise noted)

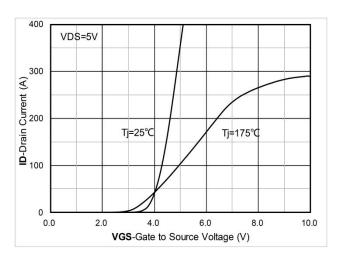
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	ID = 250µA, VGS = 0V	100	110	-	V
Drain Cut-Off Current	I _{DSS}	VDS = 80V, VGS = 0V	-	-	1	
Gate Leakage Current	I _{GSS}	VGS = ±20V, VDS = 0V	-	-	±0.1	μA
Gate Threshold Voltage	$V_{GS(th)}$	VDS = VGS, ID = 250μA	2.7	3.2	4	V
Drain-Source ON Resistance	R _{DS(ON)}	VGS = 10V, ID = 20A	-	1.8	2.2	mΩ
Dynamic Characteristics						
Input Capacitance	Ciss		-	9625	-	pF
Output Capacitance	Coss	VDS = 50V, VGS = 0V, f = 1.0MHz	-	1608	-	
Reverse Transfer Capacitance	C _{rss}			75	-	
Total Gate Charge	Qg		-	160	-	
Gate-Source Charge	Q _{gs}	VDS = 50V, VGS = 10V, ID=20A	-	31	-	nC
Gate-Drain Charge	Q _{gd}		-	37	-	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}		-	35	-	
Rise Time	t _r	VGS = 10V, VDS = 50V, RL = 2.5Ω	-	68	-	
Turn-Off Delay Time	t _{d(off)}	$RG = 6.0\Omega$	-	150	-	nS
Fall Time	t _f		-	105	-	
Drain-Source Body Diode Characteris	stics					
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 1A, VGS = 0V,T _J = 25°C	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	260	Α
Reverse Recovery Time	Trr	T _J = 25°C, IF = 100A, di/dt = 100A/us	-	97	-	nS
Reverse Recovery Charge	Qrr	13 – 20 0, 11 – 100A, di/dt – 100A/dS	-	228	-	nC

Note:

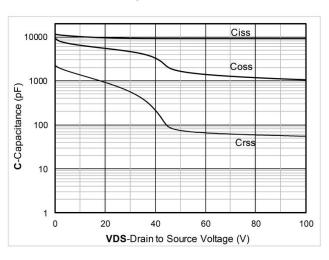
1. The test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 Ω

Typical Characteristics

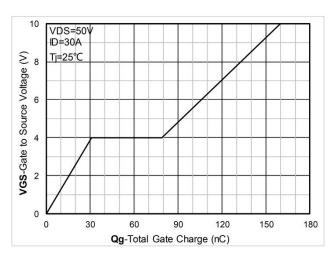




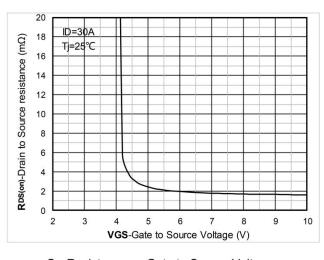
Output Characteristics



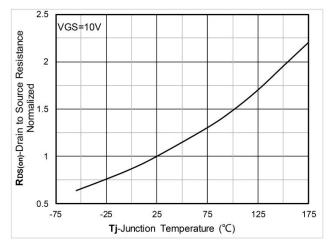
Transfer Characteristics



Capacitance Characteristics



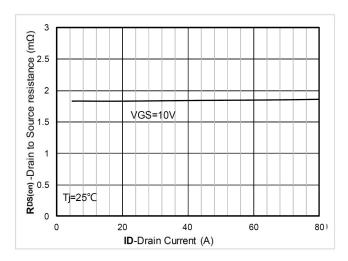
Gate Charge

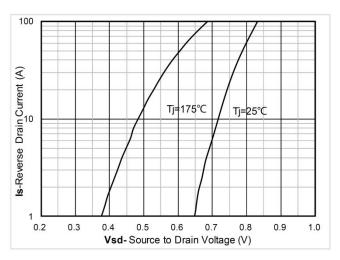


On-Resistance vs Gate to Source Voltage

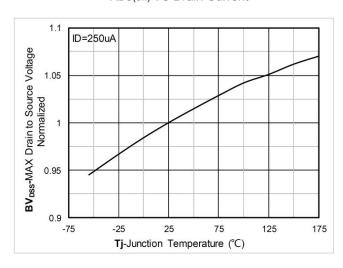
Normalized On-Resistance



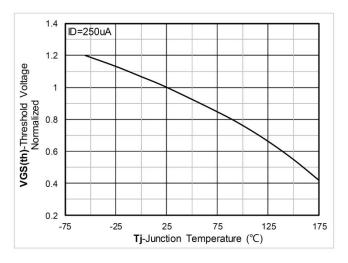




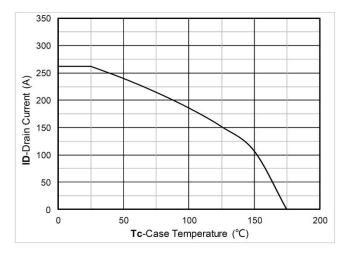
RDS(on) VS Drain Current



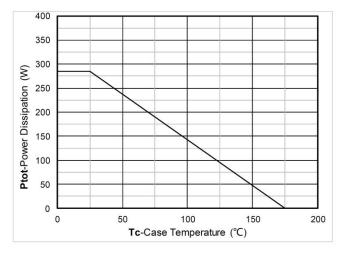
Forward characteristics of reverse diode



Normalized breakdown voltage

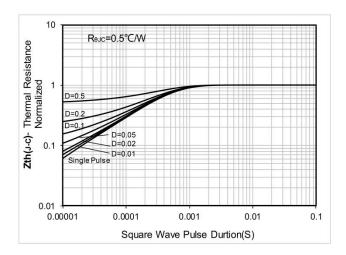


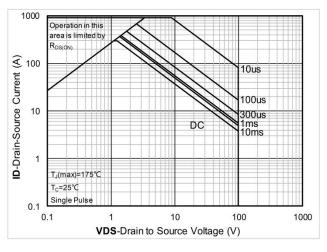
Normalized Threshold voltage



Current dissipation

Power dissipation

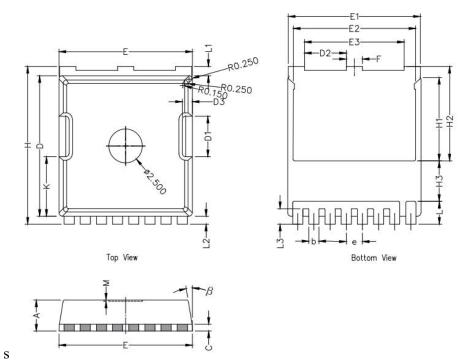




Maximum Transient Thermal Impedance

Safe Operation Area

TOLL Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
Α	2.20	2.30	2.40
b	0.65	0.75	0.85
С	0.508 REF		
D	10.25	10.40	10.55
D1	2.85	3.00	3.15
Е	9.75	9.90	10.05
E1	9.65	9.80	9.95
E2	8.95	9.10	9.25
E3	7.25	7.40	7.55
е	1.20 BSC		
F	1.05	1.20	1.35
Н	11.55	11.70	11.85
H1	6.03	6.18	6.33
H2	6.85	7.00	7.15
H3	3.00 BSC		
L	1.55	1.70	1.85
L1	0.55	0.7	0.85
L2	0.45	0.6	0.75
М	0.08 REF.		
β	8°	10°	12°
К	4.25	4.40	4.55